

DM-TFT20-439

2.0" 320x240 TRANSFLECTIVE DISPLAY

PANEL WITH CAPACITIVE TOUCH-

MCU/SPI/RGB

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1 Revision History

Date	Changes
2022-06-29	First release

2 Main Features

TFT Features

Item	Specification	Unit
Size	2.0	Inch
Resolution	320(RGB) x 240	pixel
Module Dimension	54.50 x 47.56 x 4.35	mm
Display area	40.80(H)*30.60(V)	mm
Pixel pitch	0.1275 x 0.1275	mm
TFT Controller IC	ILI9342C	-
Interface	8/9/16/18Bit MCU 3/4SPI+16/18Bit RGB Interface 3-line/4-line Serial	-
Display Color	65K/262K	colors
View Direction	Wide angle	O'clock
Display mode	Transflective /Normally Black	-
Weight	TBD	g
Operating temperature	-20~+70	°C
Storage temperature	-30~+80	°C

CTP Features

General Information Items	Specification	Unit	Note
	Main Pane		
Resolution	320(H)*240(V)	-	
Structure	G+G	-	
Controller IC	FT5436DQQ	-	
Interface	I2C	-	
Slave Adress	0x38(7bit)/8bit:0x70(Write) 0x71(Read)	-	
Touch mode	Five points and Gestures	-	-

3 Pin Description

TFT PIN Define

No.	Symbol	Description				
1	GND	Ground				
2	GND	Ground				
3	IOVCC	Supply voltage(1.65-3.3V)				
4	VCI	Supply voltage(3.3V)				
5	IM3	Interface Selection				
6	IM2	IM3				
7	IM0	IM2				
		IM0				
		Interface type				
		DB Pin in use				
		0	0	0	DBI Tyb_ 8-bit interface	DB7-DB0
		0	1	0	DBI Tyb_ 16-bit interface	DB15-DB0
0	0	1	DBI Tyb_ 9-bit interface	DB8-DB0		
0	1	1	DBI Tyb_ 18-bit interface	DB17-DB0		
1	0	1	3-Wire 9 BIT data serial interface	SDA SCL CS		
1	1	1	4-Wire 8 BIT data serial interface	SDA SCL CS RS		
8	SDA	Serial input signal. The data is applied on the rising edge of the SCL signal. If not used, fix this pin at IOVCC or GND.				
9	VSYNC	Frame synchronizing signal for RGB interface operation. fix this pin at				

		IOVCC or GND when not in use.
10	HSYNC	Line synchronizing signal for RGB interface operation. fix this pin at IOVCC or GND when not in use.
11	DOTCLK	Dot clock signal for RGB interface operation Fix this pin at IOVCC or GND when not in use.
12	ENABLE	Data enable signal for RGB interface operation. fix this pin at IOVCC or GND when not in use.
13	RD	Serves as a read signal and MCU read data at the rising edge. fix this pin at IOVCC or GND when not in use.
14	WR(SPI-RS)	(WR): Serves as a write signal and writes data at the rising edge. 4-line system (RS): Serves as command or parameter select. Fix to IOVCC or GND level when not in use.
15	RS(SPI-SCL)	This pin is used to select “Data or Command” in the parallel interface. When RS = '1', data is selected. When RS = '0', command is selected. This pin is used serial interface clock in 3-wire 9-bit / 4-wire 8-bit serial data interface. If not used, this pin should be connected to IOVCC or GND. RS_SCL1
16	CS	Chip select input pin (“Low” enable). This pin can be permanently fixed “Low” in MPU interface mode only. CSX1 is equal
17	RESET	This signal will reset the device and must be applied to properly initialize the chip. Signal is active low. RESX1 is equal to RESX.
18-35	DB17-DB0	18-bit parallel bi-directional data bus for MCU system and RGB interface mode Fix to GND level when not in use
36	NC	--
37	NC	--
38	LEDK	Cathode pin OF backlight
39	NC	--
40	LEDA	Anode pin OF backlight
41	XR	No connected
42	YU	No connected
43	XL	No connected
44	YD	No connected

45	GND	Ground
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CTP PIN Define

NO.	SYMBOL	DISCRIPTION	I/O
1	GND	Ground.	P
2	VDDIO	I/O power supply voltage.	P
3	VDD	Supply voltage.	P
4	SCL	I2C clock input.	I
5	SDA	I2C data input and output	I/O
6	INT	External interrupt to the host	I
7	RST	External Reset, Low is active	I
8	GND	Ground.	P

5 Electrical Characteristics

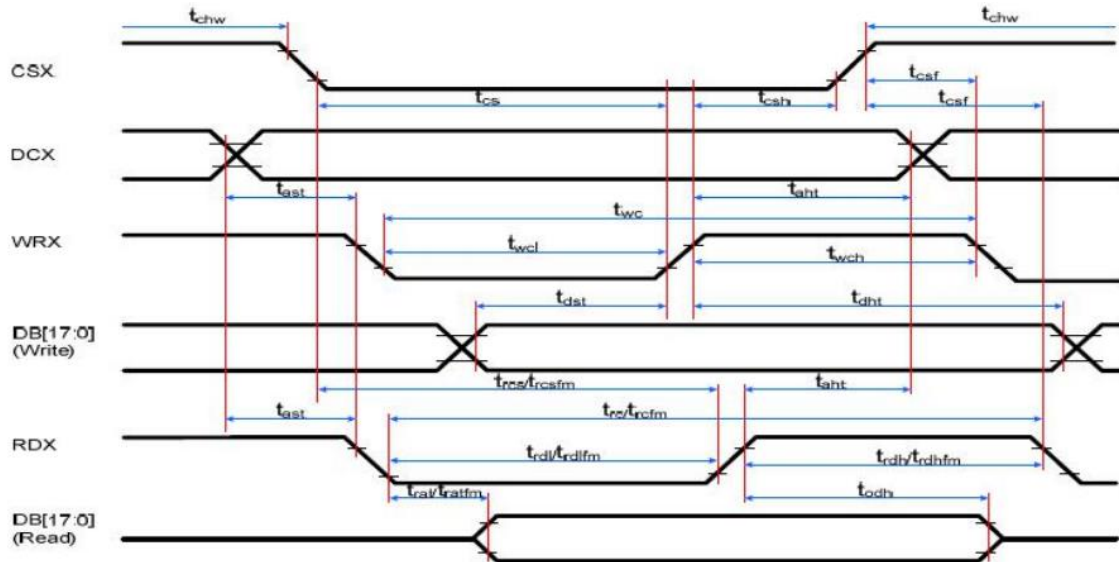
Item		Symbol	Min	Typ.	Max	Unit
Digital Supply Voltage	Absolute Maximum Rating	VCI	-0.3		4.2	V
Digital interface supply Voltage	Absolute Maximum Rating	IOVCC	-0.3		3.3	V
Operating Temperature	Absolute Maximum Rating	TOP	-20		+70	°C
Storage Temperature	Absolute Maximum Rating	TST	-30		+80	°C
Digital Supply Voltage		VCI	2.5	2.8/3.3	3.6	V
Digital interface supply Voltage		IOVCC	1.65	1.8	3.3	V
Normal mode Current		IDD	--	5	--	mA
Level input voltage		V _{IH}	0.7*IOVCC	--	IOVCC	V
		V _{IL}	GND	--	0.3*IOVCC	V
Level output voltage		V _{OH}	0.8*IOVCC	--	IOVCC	V
		V _{OL}	GND	--	0.2*IOVCC	V

6 Optical Characteristics

Item	Symbol	Min	Typ	Max	Unit
Forward Current	I _F	30	40	-	mA
Forward Voltage	V _F	--	12	-	V
LCM Luminance	LV	250	300	-	cd/m ²
LED life time	H _r	50000	--	-	Hour
Uniformity	Avg	80	--	-	%

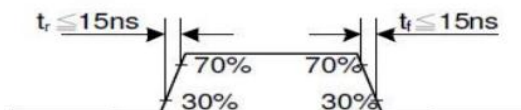
7 AC Characteristics

7.1 Display Parallel 8/9/16/18-bit Interface Timing Characteristics (8080 system)

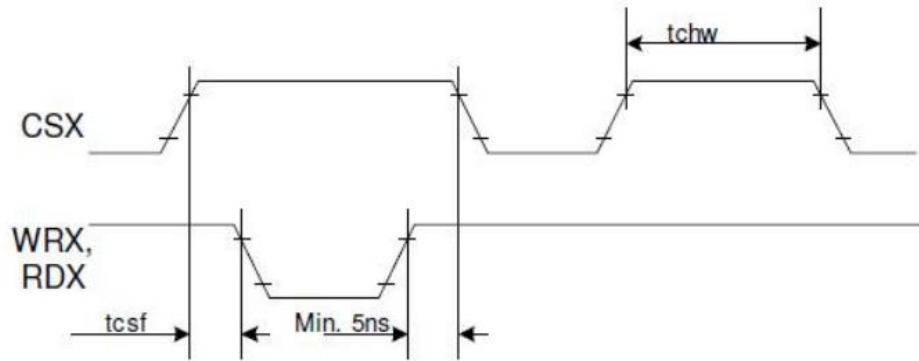


Signal	Symbol	Parameter	min	max	Unit	Description
DCX	tast	Address setup time	0	-	ns	
	taht	Address hold time (Write/Read)	10	-	ns	
CSX	tchw	CSX "H" pulse width	0	-	ns	
	tcs	Chip Select setup time (Write)	15	-	ns	
	trcs	Chip Select setup time (Read ID)	45	-	ns	
	trcsfm	Chip Select setup time (Read FM)	355	-	ns	
WRX	tcsf	Chip Select Wait time (Write/Read)	10	-	ns	
	twc	Write cycle	66	-	ns	
	twrh	Write Control pulse H duration	15	-	ns	
RDX (FM)	twrl	Write Control pulse L duration	15	-	ns	
	trcfm	Read Cycle (FM)	450	-	ns	
	trdhfm	Read Control H duration (FM)	90	-	ns	
RDX (ID)	trdlfm	Read Control L duration (FM)	355	-	ns	
	trc	Read cycle (ID)	160	-	ns	
	trdh	Read Control pulse H duration	90	-	ns	
D[17:0], D[17:10]&D[8:1], D[17:10], D[17:9]	trdl	Read Control pulse L duration	45	-	ns	
	tdst	Write data setup time	10	-	ns	For maximum CL=30pF For minimum CL=8pF
	tdht	Write data hold time	10	-	ns	
	trat	Read access time	-	40	ns	
	tratfm	Read access time	-	340	ns	
trod	Read output disable time	20	80	ns		

Note: $T_a = -30$ to 70 °C, $IOVCC=1.65V$ to $2.8V$, $VCI=2.6V$ to $3.3V$, $GND=0V$.

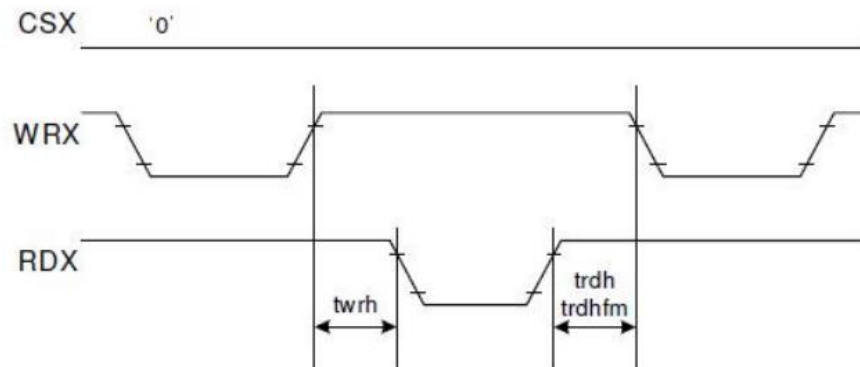


CSX timings :



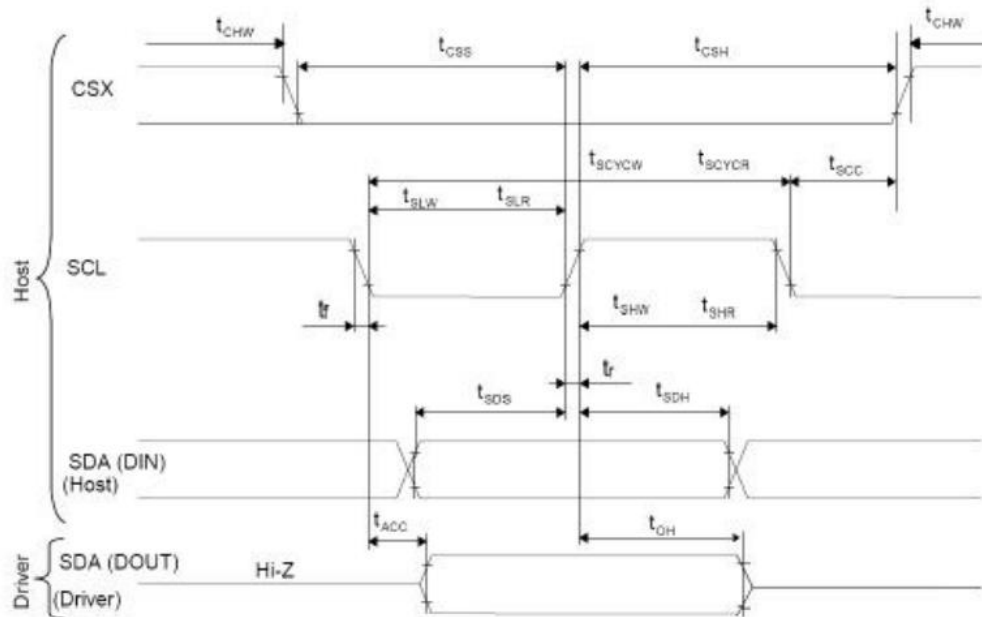
Note: Logic high and low levels are specified as 30% and 70% of IOVCC for Input signals.

Write to read or read to write timings:



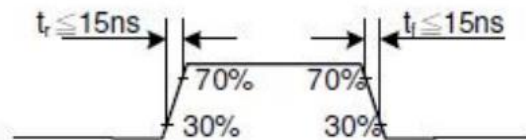
Note: Logic high and low levels are specified as 30% and 70% of IOVCC for Input signals.

7.2 Display Serial Interface Timing Characteristics (3-line SPI system)

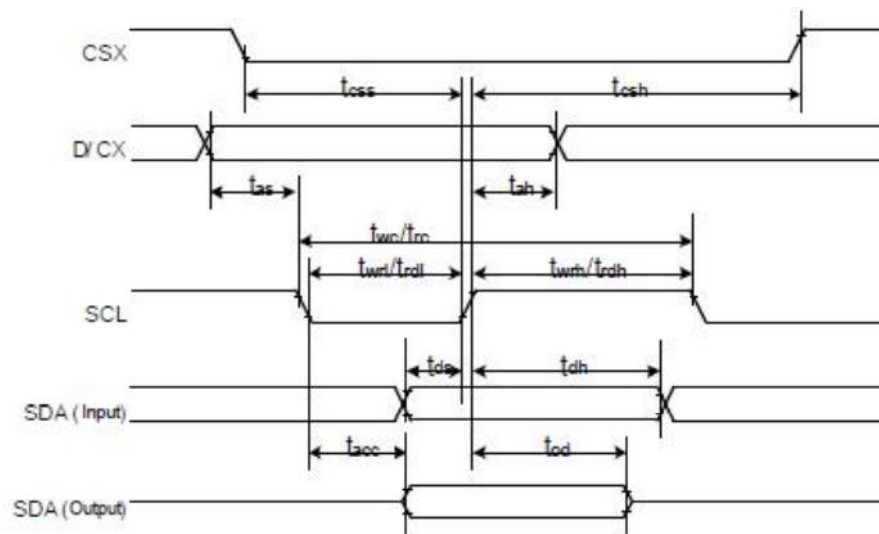


Signal	Symbol	Parameter	min	max	Unit	Description
SCL	tscycw	Serial Clock Cycle (Write)	100	-	ns	
	tshw	SCL "H" Pulse Width (Write)	35	-	ns	
	tslw	SCL "L" Pulse Width (Write)	35	-	ns	
	tscycr	Serial Clock Cycle (Read)	150	-	ns	
	tshr	SCL "H" Pulse Width (Read)	60	-	ns	
SDA (Input)	tsdw	Data setup time (Write)	30	-	ns	
	tsdh	Data hold time (Write)	30	-	ns	
SDA (Output)	tacc	Access time (Read)	10	-	ns	
	toh	Output disable time (Read)	15	50	ns	
CSX	tsc	SCL-CSX	20	-	ns	
	tchwh	CSX "H" Pulse Width	40	-	ns	
	tcsw	CSX-SCL Time(write)	30	-	ns	
	tcsh		30	-	ns	

Note: $T_a = 25\text{ }^\circ\text{C}$, $I_{OVCC}=1.65\text{V to }2.8\text{V}$, $V_{CI}=2.6\text{V to }3.3\text{V}$, $AGND=GND=0\text{V}$

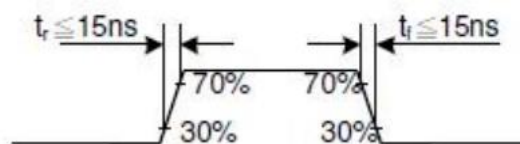


7.3 Display Serial Interface Timing Characteristics (4-line SPI system)

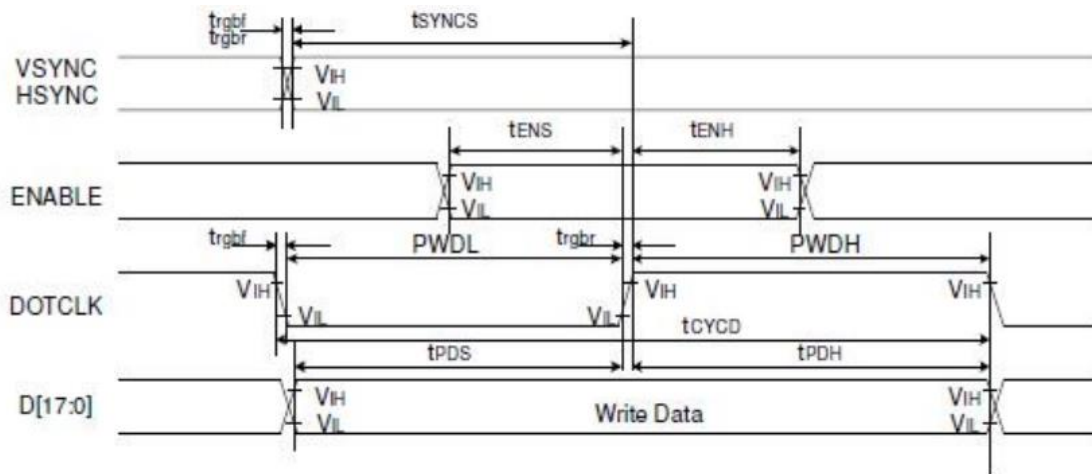


Signal	Symbol	Parameter	min	max	Unit	Description
CSX	t_{css}	Chip select time (Write)	30	-	ns	
	t_{csh}	Chip select hold time (write)	30	-	ns	
SCL	t_{wc}	Serial clock cycle (Write)	100	-	ns	
	t_{wrh}	SCL "H" pulse width (Write)	35	-	ns	
	t_{wrl}	SCL "L" pulse width (Write)	35	-	ns	
	t_{rc}	Serial clock cycle (Read)	150	-	ns	
	t_{rdh}	SCL "H" pulse width (Read)	60	-	ns	
	t_{rdl}	SCL "L" pulse width (Read)	60	-	ns	
D/CX	t_{as}	D/CX setup time	10	-		
	t_{ah}	D/CX hold time (Write / Read)	10	-		
SDA (Input)	t_{ds}	Data setup time (Write)	30	-	ns	
	t_{dh}	Data hold time (Write)	30	-	ns	
SDA (Output)	t_{acc}	Access time (Read)	-	50	ns	For maximum $C_L=30pF$
	t_{od}	Output disable time (Read)	15	50	ns	For minimum $C_L=8pF$

Note: $T_a = 25^\circ C$, $IOVCC=1.65V$ to $2.8V$, $VCI=2.6V$ to $3.3V$, $AGND=GND=0V$

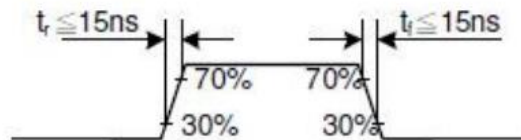


7.4 Parallel 16/18BIT RGB Interface Timing Characteristics



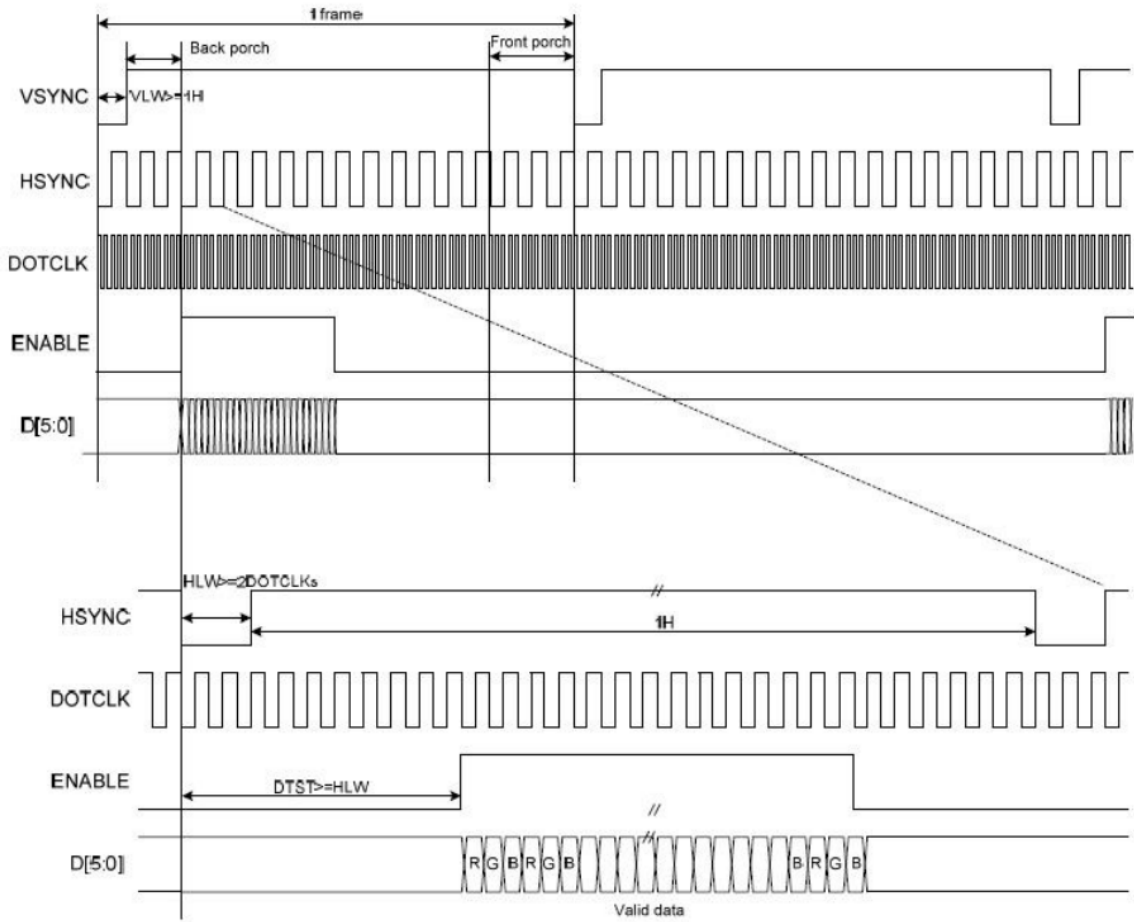
Signal	Symbol	Parameter	min	max	Unit	Description
VSYNC / HSYNC	t_{SYNCs}	VSYNC/HSYNC setup time	15	-	ns	18/16-bit bus RGB interface mode
	t_{SYNCH}	VSYNC/HSYNC hold time	15	-	ns	
DE	t_{ENS}	DE setup time	15	-	ns	
	t_{ENH}	DE hold time	15	-	ns	
D[17:0]	t_{POS}	Data setup time	15	-	ns	
	t_{PDH}	Data hold time	15	-	ns	
DOTCLK	PVDH	DOTCLK high-level period	33	-	ns	
	PVDL	DOTCLK low-level period	33	-	ns	
	t_{CYCD}	DOTCLK cycle time(18 bit)	100	-	ns	
	$t_{\text{rbr}}, t_{\text{fbr}}$	DOTCLK,HSYNC,VSYNC rise/fall time	-	15	ns	
VSYNC / HSYNC	t_{SYNCs}	VSYNC/HSYNC setup time	15	-	ns	6-bit bus RGB interface mode
	t_{SYNCH}	VSYNC/HSYNC hold time	15	-	ns	
DE	t_{ENS}	DE setup time	15	-	ns	
	t_{ENH}	DE hold time	15	-	ns	
D[17:0]	t_{POS}	Data setup time	15	-	ns	
	t_{PDH}	Data hold time	15	-	ns	
DOTCLK	PVDH	DOTCLK high-level pulse period	25	-	ns	
	PVDL	DOTCLK low-level pulse period	25	-	ns	
	t_{CYCD}	DOTCLK cycle time	50	-	ns	
	$t_{\text{rbr}}, t_{\text{fbr}}$	DOTCLK,HSYNC,VSYNC rise/fall time	-	15	ns	

Note: $T_a = -30$ to 70 °C, $IOVCC=1.65V$ to $2.8V$, $VCI=2.6V$ to $3.3V$, $AGND=GND=0V$

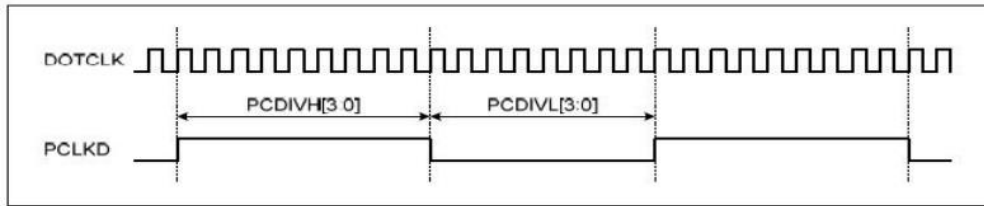


7.5 RGB Interface Timing

The timing chart of 18-/16-bit RGB interface mode is shown as below.



VLW : VSYNC Low Width
 HLW : HSYNC Low Width
 DTST : Data Transfer Startup Time

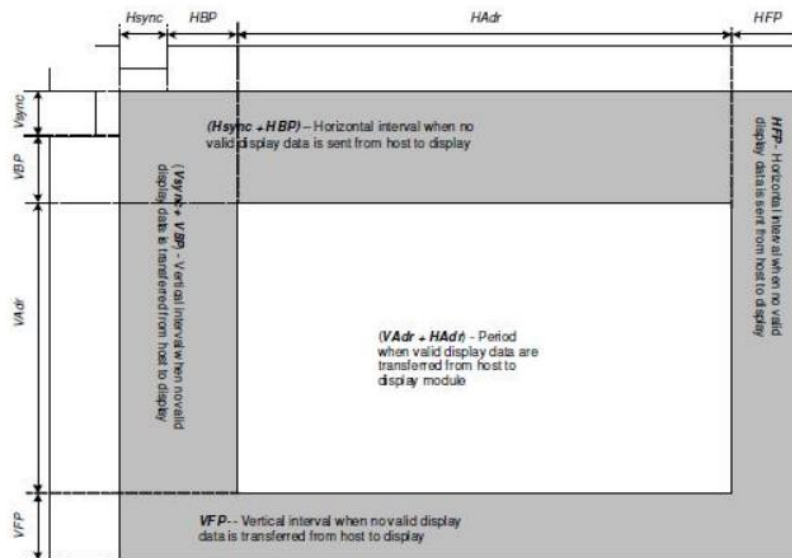


Note 1: The DE signal is not needed when RGB interface SYNC mode is selected.

Note 2: VSPL='0', HSPL='0', DPL='0' and EPL='1' of "Interface Mode Control (B0h)" command.

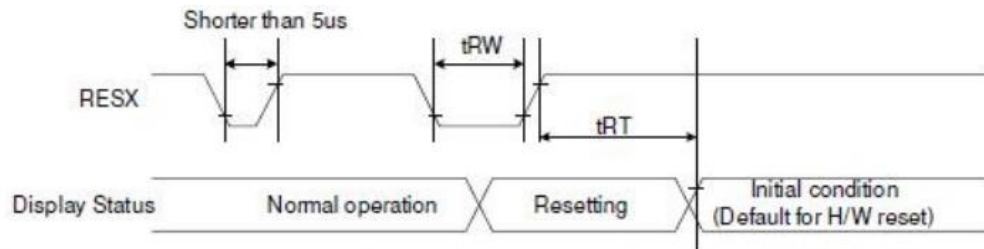
Note 3: In 6-bit RGB interface mode, each dot of one pixel (R, G and B) is transferred in synchronization with DOTCLK.

Note 4: In 6-bit RGB interface mode, set the cycles of VSYNC, HSYNC and DE to 3 multiples of DOTCLK.



Parameters	Symbols	Condition	Min.	Typ.	Max.	Units
Horizontal Synchronization	Hsync		2	10	16	DOTCLK
Horizontal Back Porch	HBP		2	20	24	DOTCLK
Horizontal Back Porch(By pass mode)*	HBP(BP)		58	68	200	DOTCLK
Horizontal Address	HAdr		-	320	-	DOTCLK
Horizontal Front Porch	HFP		2	10	16	DOTCLK
Vertical Synchronization	Vsync		1	2	4	Line
Vertical Back Porch	VBP		1	2	-	Line
Vertical Address	VAdr		-	240	-	Line
Vertical Front Porch	VFP		3	4	-	Line

7.6 Reset Timing Characteristics



Signal	Symbol	Parameter	Min	Max	Unit
RESX	tRW	Reset pulse duration	10		uS
	tRT	Reset cancel		5 (note 1,5)	mS
				120 (note 1,6,7)	mS

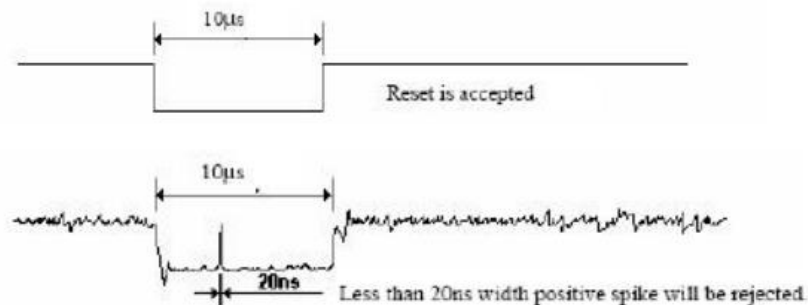
Note 1: The reset cancel includes also required time for loading ID bytes, VCOM setting and other settings from NV memory to registers. This loading is done every time when there is HW reset cancel time (tRT) within 5 ms after a rising edge of RESX.

Note 2: Spike due to an electrostatic discharge on RESX line does not cause irregular system reset according to the table below: -

RESX Pulse	Action
Shorter than 5us	Reset Rejected
Longer than 10us	Reset
Between 5us and 10us	Reset starts

Note 3: During the Resetting period, the display will be blanked (The display is entering blanking sequence, which maximum time is 120 ms, when Reset Starts in Sleep Out –mode. The display remains the blank state in Sleep In -mode.) And then return to Default condition for Hardware Reset.

Note 4: Spike Rejection also applies during a valid reset pulse as shown below:




Note 5: When Reset applied during Sleep In Mode.

Note 6: When Reset applied during Sleep Out Mode.

Note 7: It is necessary to wait 5msec after releasing RESX before sending commands. Also Sleep Out command cannot be sent for 120msec.

8 Reliability

Test Item	Content of Test	Test Condition	Note
High Temperature Storage	Endurance test applying the high storage temperature for a long time.	80°C 200hrs	2
Low Temperature Storage	Endurance test applying the high storage temperature for a long time.	-30°C 200hrs	1,2
High Temperature Operation	Endurance test applying the electric stress (Voltage & Current) and the thermal stress to the element for a long time.	70°C 200hrs	-
Low Temperature Operation	Endurance test applying the electric stress under low temperature for a long time.	-20°C 200hrs	1
High Temperature/ Humidity Operation	The module should be allowed to stand at 60°C,90%RH max, for 96hrs under no-load condition excluding the polarizer. Then taking it out and drying it at normal temperature.	60°C,90%RH 96hrs	1,2
Thermal Shock Resistance	The sample should be allowed stand the following 10 cycles of operation. -20°C 25°C 70°C ⁺  30min 5min 30min. 1 cycle ⁺	-20°C/70°C 10 cycles	-
Vibration Test	Endurance test applying the vibration during transportation and using.	Total fixed amplitude: 15mm; Vibration: 10~55Hz; One cycle 60 seconds to 3 directions of X, Y, Z, for each 16 minutes.	3
Static Electricity Test	Endurance test apply the electric stress to the terminal.	VS=800V, RS=1.5kΩ, CS=100pF, 1 time.	-

Note1: No dew condensation to be observed.

Note2: The function test shall be conducted after 4 hours storage at the normal. Temperature and humidity after remove from the rest chamber.

Note3: Test performed on product itself, not inside a container

9 Warranty and Conditions

<http://www.displaymodule.com/pages/faq>